

Title (en)

THERMOFORMING PACKAGING MACHINE, METHOD AND PACKAGING MATERIAL

Title (de)

TIEFZIEHVERPACKUNGSMASCHINE, VERFAHREN UND VERPACKUNG

Title (fr)

MACHINE D'EMBALLAGE PAR THERMOFORMAGE, PROCÉDÉ ET MATÉRIAU D'EMBALLAGE

Publication

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Application

**EP 20820097 A 20201203**

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Abstract (en)

[origin: WO2021110795A1] The invention relates to a thermoforming packaging machine (1) for creating packaging materials (12) from a first film (8) and a second film (10), wherein the first and the second film (8, 10) are each conveyed, preferably in a clocked manner, through the thermoforming machine (1) along a conveying path (R1, R2). The thermoforming packaging machine (1) comprises a sealing station (3) which is configured to seal the second film (10) to the first film (8) in a sealing region (31), a film cutting station (22) which is designed to make at least two cuts (26) in the second film (10) on the conveying path (R2) upstream of the sealing station (3), and a presealing station (23) which is designed to seal a presealing region (27) of the second film (10) at least partially onto the first film (8) on the conveying path (R2) upstream of the sealing station (2), the cuts (26) being arranged in the presealing region (27).

IPC 8 full level

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US 2014331611 A1 20141113 - MEYER KLAUS [DE], et al

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